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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10076244	02/13/2002	438	108	2813	Nema Bereznay

****APPLICANTS:** Aliyu Yakub; Chooi Simon; Zhou Meisheng; Sudijono John; Gupta Subhash; Roy Sudipto;

Nema has
the patent
case.

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****CONTINUING DATA VERIFIED:**

This application is a CIP of 09/612,576 07/07/2000 ABN

**** FOREIGN APPLICATIONS VERIFIED:**

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			CS99-343C
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Method of copper/copper surface bonding using a conducting polymer for application in IC chip bonding			

U.S. DEPT. OF COMM/PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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